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1. (Twice amended) A method of bonding balls of solder to bond pads on a substrate comprising:

3 contemporaneously retaining at least two balls of solder over different
4 respective bond pads on a substrate in the absence of flux; and
5 with the at least two balls of solder so retained, exposing the at least
6 two balls of solder to bonding conditions effective to bond the at least two
7 balls of solder with their associated bond pads.

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9 2. (Twice amended) The method of claim 1, wherein exposing
10 comprises laser-bonding the at least two balls of solder.

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12 Cancel claim 41.
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1 New Claims

2 3 45. The method of claim 1, wherein exposing comprises melting the
3 at least two balls.

4 46. A method of bonding balls of solder to bond pads on a substrate
5 comprising:

6 C 2 7 contemporaneously retaining first and second balls of solder over
8 different respective first and second bond pads on a substrate in the absence
9 of flux; and

10 11 with the first and second balls of solder so retained, sequentially
12 exposing the first and second solder balls to bonding conditions effective to
13 (i) melt each of the first and second balls of solder and then (ii) cool each
14 of the first and second molten balls of solder to bond each of the first and
15 second balls of solder with their associated first and second bond pads.

16 17 47. The method of claim 46, wherein exposing comprises sequentially
18 laser-bonding each of the first and second balls of solder.